

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW RESONATOR \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDR315.12M-S6 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ DATE 日期: \_\_\_\_\_ 2015-10-17 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



## 1. Scope

This specification shall cover the characteristics of 1-port SAW resonator with R315.12M used for remote-control security.

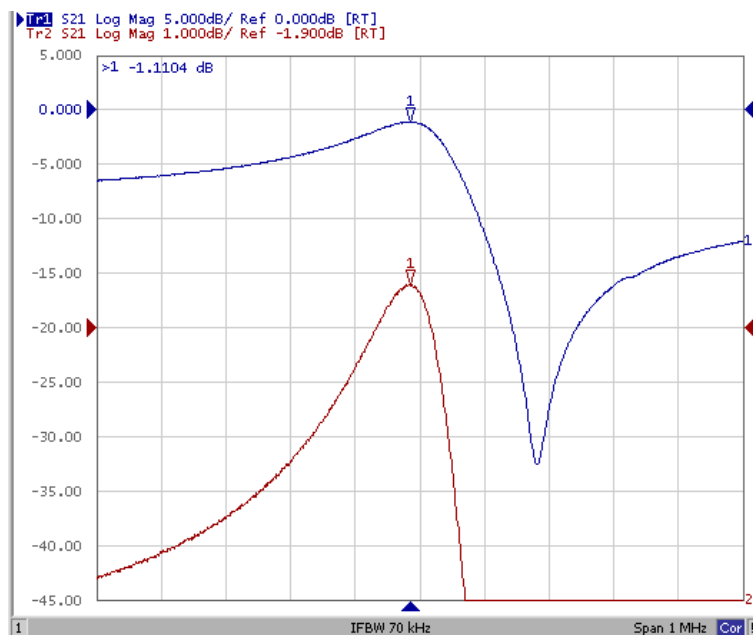
## 2. Electrical Specification

### 2.1 Maximum Rating

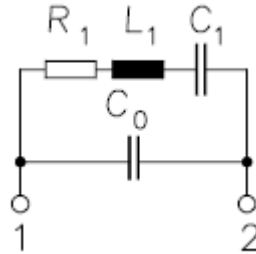
DC Voltage VDC	10V
AC Voltage Vpp	10V 50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
Source Power	0dBm

### 2.2 Electronic Characteristics

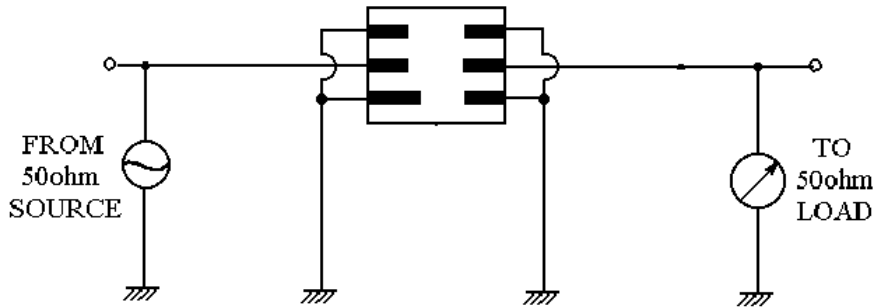
Item	Unites	Minimum	Typical	Maximum
Center Frequency	MHz	315.045	315.120	315.195
Insertion Loss	dB		1.4	1.9
Quality Factor	Unload Q	8000	12800	
	50Ω Loaded Q	1000	2000	
Temperature Stability	Turnover Temperature	°C	10	25
	Freq.temp.Coefficient	ppm/°C		0.032
Frequency Aging	ppm/yr		<±10	
DC. Insulation Resistance	MΩ	1.0		
Transducer Static Capacitance C0	pF		2.13	



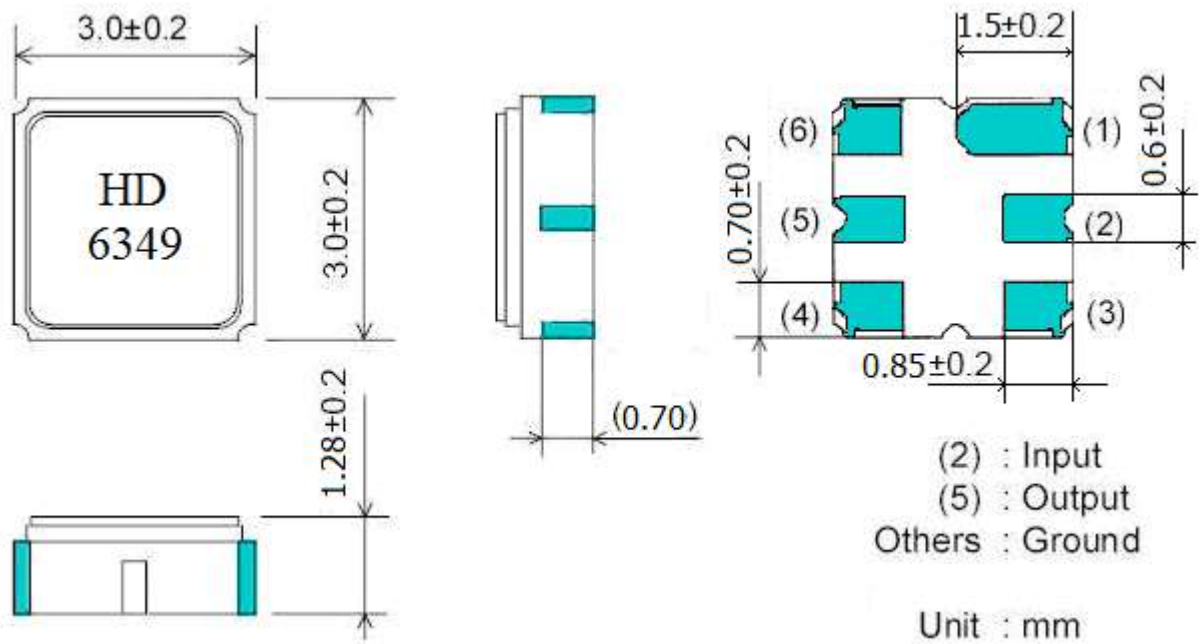
2.3 Equivalent LC Model



3. Test Circuit



4. Dimension



- 1. **HD**: Manufacture's logo
- 2. 6349: Model code

## 5. Environment Characteristic

### 5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

### 5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

### 5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2-2.

### 5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-2.

### 5-5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2-2.

### 5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2-2.

### 5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-2.

## 6. Remark

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.